S3AB thru S3MB

SURFACE MOUNT
GLASS PASSIVATED RECTIFIERS

REVERSE VOLTAGE - **50** to **1000**Volts
POWER DISSIPATION - **3.0** Amperes

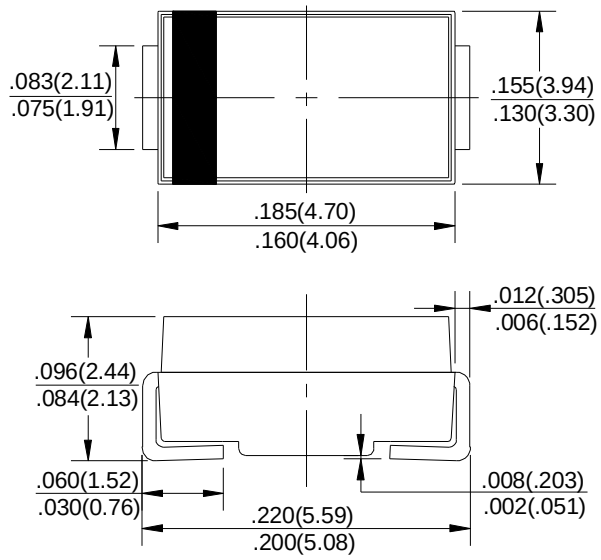
FEATURES

- Glass passivated chip
- For surface mounted applications
- Low reverse leakage current
- Low forward voltage drop
- High current capability
- Plastic material has UL flammability classification 94V-0

MECHANICAL DATA

- Case： Molded Plastic
- Polarity:Color band denotes cathode
- Weight: 0.003 ounces,0.093 grams
- Mounting position: Any

SMB



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25℃ ambient temperature unless otherwise specified.
Single phase, half wave ,60Hz, resistive or inductive load.
For capacitive load, derate current by 20%

CHARACTERISTICS	SYMBOL	S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	UNIT
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @T_L=75 ℃	$I_{(AV)}$	3.0							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed On Rated Load (JEDEC Method)	I_{FSM}	200							A
Maximum Forward Voltage at 3.0A DC	V_F	1.2							V
Maximum DC Reverse Current @T_J=25℃ at Rated DC Blocking Voltage @T_J=100℃	I_R	5.0 250							uA
Typical Junction Capacitance (Note1)	C_J	40							pF
Typical Thermal Resistance (Note2)	$R_{\theta JL}$	10							℃/W
Typical Thermal Resistance (Note3)	$R_{\theta JA}$	50							℃/W
Operating Temperature Range	T_J	-55 to +150							℃
Storage Temperature Range	T_{STG}	-55 to +150							℃

NOTES:1.Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.
2.Thermal resistance junction to lead.
3.Thermal resistance junction to ambient.

RATING AND CHARACTERISTIC CURVES
S3AB thru S3MB

FIG. 1 - FORWARD CURRENT DERATING CURVE

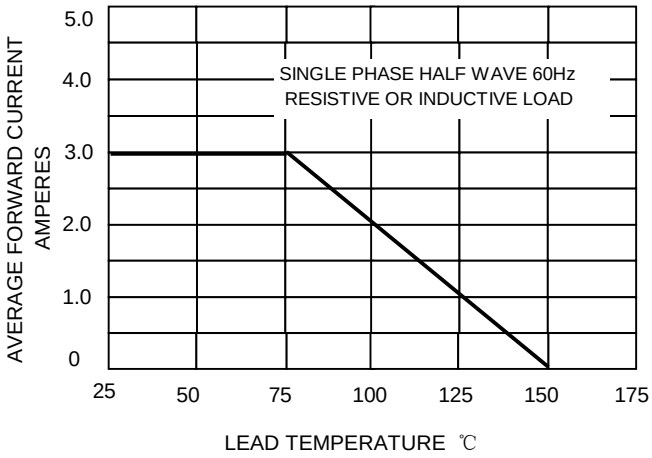


FIG.2 - MAXIMUM NON-REPETITIVE SURGE CURRENT

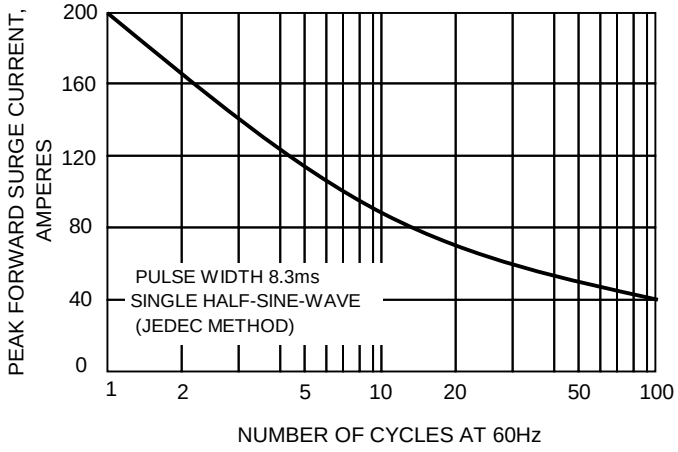


FIG.3-TYPICAL FORWARD CHARACTERISTICS

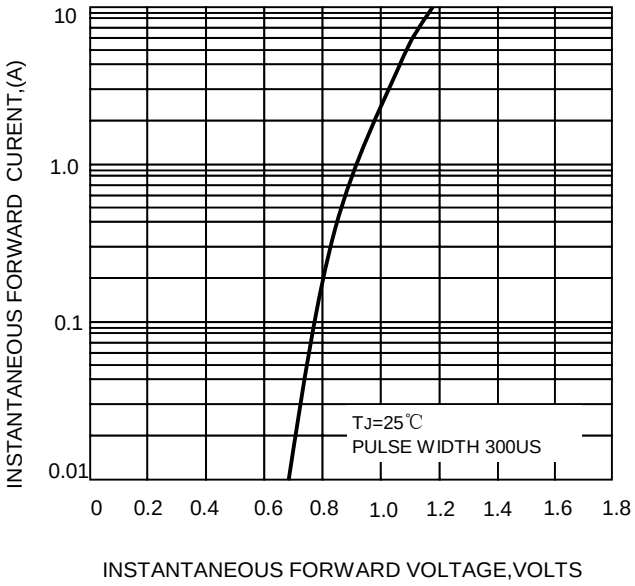


FIG.4-TYPICAL REVERSE CHARACTERISTICS

